

programming each of the integrated circuits[circuit] with respective[an] electronic identification information distinguishing the integrated circuits from one another; and

marking each of the integrated circuits[circuit] with respective[an] optical identification code which corresponds with the respective electronic identification information.

2. (Amended) The method of claim 1, further comprising the steps of:

reading the optical identification code on each of the integrated circuits;

and

associating the optical identification code on each of the integrated circuits with the corresponding electronic identification information.

3. (Amended) The method of claim 2 wherein the step of associating the optical identification code on each of the integrated circuits with the corresponding electronic identification information includes the step of accessing a look-up table.

2. (Amended) The method of claim 1 wherein the step of programming each of the integrated circuits[circuit] with [an] electronic identification information includes the step of programming one of a plurality of programmable links.

3. (Amended) The method of claim 1 wherein the step of marking each of the integrated circuits[circuit] with [an] optical identification code includes the step of placing an adhesive label on each of the integrated circuits[circuit].

4. (Amended) The method of claim 1 wherein the step of marking each of the integrated circuits[circuit] with [an] optical identification code includes the step of inscribing a symbol on each of the integrated circuits[circuit].

*Sub B3*

7. (Amended) In a plurality of substantially identical[an] integrated circuits[circuit] formed on a common substrate, each of the integrated circuits including[which includes] a programmable circuit for storing respective[an] electronically readable identification code which distinguishes[identifies] the integrated circuits[circuit] from one another, a method of identifying the integrated circuits[circuit], comprising the steps of:

marking each of the integrated circuits[circuit] with respective[an] optical identification code; and

associating the optical identification code on each of the integrated circuits with the respective electronically readable identification code.

*7.8* 8. (Amended) The method of claim 7 wherein the step of associating the optical identification code on each of the integrated circuits with the respective electronically readable identification code includes the steps of:

reading the electronically readable identification code stored in each of the integrated circuits;

reading the optical identification code marked on each of the integrated circuits; and

correlating the read electronically readable identification code with the read optical identification code for each of the integrated circuits.

9. (Amended) The method of claim 8 wherein the step of correlating the read electronically readable identification code with the read optical identification code for each of the integrated circuits includes the step of creating a look-up table.

*8.10* 10. (Amended) The method of claim 7 wherein the step of associating the optical identification code on each of the integrated circuits with the respective electronically readable identification code includes the step of encoding identical data in the optical and electronically readable identification codes.

*10*

*Sub 4 P*

11. (Amended) A wafer comprising a plurality of dies, each die including an[An] integrated circuit having [, comprising:

]a programmable identification circuit that stores[operable to store] identification data, and each die having[; and

]an optical identification mark positioned thereon and encoding information corresponding to the identification data.

*11 12* 12. (Amended) The wafer[integrated circuit] of claim 11 wherein the programmable identification circuit includes a plurality of programmable links.

*13 12* 13. (Amended) The wafer[integrated circuit] of claim 11 wherein the optical identification mark encodes information identical to the identification data.

14. (Amended) A plurality of[An] integrated circuit chips[chip], each comprising:

a housing;

an integrated circuit enclosed within the housing and including an identification circuit that stores[operable to store] identification data distinguishing each of the integrated circuit chips from one another; and

an optical mark positioned on an exterior surface of the housing and <sup>being accessed through a lookup table to</sup> encoding identification information corresponding to the identification data.

15. (Amended) The integrated circuit chips[chip] of claim 14, further comprising electrical contacts connected to said housing and adapted to provide electrical connection between the integrated circuit and circuitry external to the housing.

16. (Amended) The integrated circuit chips[chip] of claim 14 wherein the optical mark is a first optical mark encoding first identification information, and further comprising a second optical mark positioned[position] on the integrated circuit enclosed within the housing and encoding second identification information corresponding to the identification data.

*Amend*

17. (Amended) The integrated circuit chips[chip] of claim 16 wherein the first identification information is identical to the second identification information.

18. (Amended) The integrated circuit chips[chip] of claim 14 wherein the identification information is the same as the identification data.

Please add the following new claims:

*5*  
19. The method of claim 1 wherein the step of marking each of the integrated circuits includes the step of marking respective portions of the substrate on which the integrated circuits are formed.

*9*  
20. The method of claim 1 wherein the step of marking each of the integrated circuits includes the step of marking respective portions of the substrate on which the integrated circuits are formed.

*13*  
21. The wafer of claim 1 wherein the identification data uniquely distinguishes each of the dies.

*Sub B5*  
22. A method of identifying a plurality of substantially identical integrated circuits formed on a common substrate, each of the integrated circuits being formed on a respective one of a plurality of substrate dies, the method comprising:

programming each of the plurality of integrated circuits with respective electronic identification information for each of the integrated circuits; and

marking each of the dies with optical identification code which corresponds with the respective electronic identification information.

*20*  
23. The method of claim 22 wherein the electronic identification information is distinct for each of the integrated circuits.

*12*